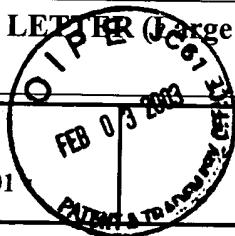


AMENDMENT TRANSMITTAL LETTER (Large Entity)

Applicant(s):

Docket No.

IIZ.003D2

Serial No.
09/920,713Filing Date
August 3, 2001Examiner
F. ToledoGroup Art Unit
2823

Invention: SEMICONDUCTOR APPARATUS AND METHOD FOR FABRICATING THE SAME (To be Amended)

TO THE ASSISTANT COMMISSIONER FOR PATENTS:

Transmitted herewith is an amendment in the above-identified application.

The fee has been calculated and is transmitted as shown below.

CLAIMS AS AMENDED

	CLAIMS REMAINING AFTER AMENDMENT	HIGHEST # PREV. PAID FOR	NUMBER EXTRA CLAIMS PRESENT	RATE	ADDITIONAL FEE
TOTAL CLAIMS	7 -	20 =	0	x \$18.00	\$0.00
INDEP. CLAIMS	2 -	3 =	0	x \$84.00	\$0.00
Multiple Dependent Claims (check if applicable) <input type="checkbox"/>					\$0.00
TOTAL ADDITIONAL FEE FOR THIS AMENDMENT					\$0.00

No additional fee is required for amendment.

Please charge Deposit Account No. in the amount of
A duplicate copy of this sheet is enclosed.

A check in the amount of to cover the filing fee is enclosed.

The Commissioner is hereby authorized to charge payment of the following fees associated with this communication or credit any overpayment to Deposit Account No. 50-0238
A duplicate copy of this sheet is enclosed.

Any additional filing fees required under 37 C.F.R. 1.16.

Any patent application processing fees under 37 CFR 1.17.

ANDREW J. TELESZ, JR.
REG. NO. 33,581VOLENTINE FRANCOS, P.L.L.C.
12200 SUNRISE VALLEY DRIVE, SUITE 150
RESTON, VA 20191

TEL. NO. (703) 715-0870

I certify that this document and fee are being deposited on FEB 03 2003 with the U.S. Postal Service as first class mail under 37 C.F.R. 1.8 and is addressed to the Assistant Commissioner for Patents, Washington, D.C. 20231.

Signature of Person Mailing Correspondence

Typed or Printed Name of Person Mailing Correspondence

cc:

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#5/B
2-6-03
IIZ.003D2
JPA

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re PATENT APPLICATION of

Takashi Ohsumi

Group Art Unit: 2823

Serial No.: 09/920,713

Examiner: F. Toledo

Filed: August 3, 2001

For: SEMICONDUCTOR APPARATUS AND METHOD FOR FABRICATING
THE SAME (To Be Amended)

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TECHNOLOGY CENTER 2800,
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AMENDMENT

Honorable Assistant Commissioner for Patents
Washington, D.C. 20231

Date: February 3, 2003

Sir:

In response to the Office Action dated November 6, 2002, the following
amendments and remarks are respectfully submitted in connection with the above-
identified application.

In the Title:

Please amend the title to read --A METHOD FOR FABRICATING A
SEMICONDUCTOR APPARATUS INCLUDING A SEALING MEMBER WITH
REDUCED THERMAL STRESS--.

In the Abstract:

Please cancel the Abstract and replace with the Abstract attached herewith.